

SEMICONDUCTOR PACKAGE

ABSTRACT

6 A semiconductor package comprises a first chip, a substrate, a middle layer, a second chip, and an encapsulant. The first chip has an active surface and a high-frequency element defining a high-frequency area on the active surface. The substrate supports the first chip and is electrically connected to the first chip. The middle layer is disposed on the first chip and has a recess corresponding to the high-frequency area. The second chip is disposed on the middle layer and electrically connected to either the first chip or the substrate. The encapsulant encapsulates the first chip, the middle layer, the second chip, and a part of the substrate.